EPCOS

SAW Components

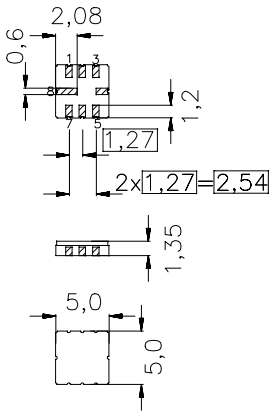
Data Sheet B3559

Data Sheet

Ceramic package **QCC8C**

Features

- RF low-loss filter for remote control receivers
- Package for **S**urface **M**ounted **T**echnology (**SMT**)
- Balanced and unbalanced operation possible



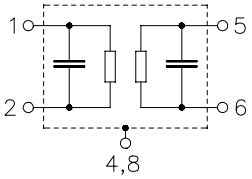
typ. dimensions in mm, approx. weight 0,1 g

Terminals

- Ni, gold plated

Pin configuration

1	Input Ground
2	Input
5	Output
6	Output Ground
4,8	Case - Ground
3,7	to be grounded



Type	Ordering code	Marking and package according to	Packing according to
B3559	B39351-B3559-U310	C61157-A7-A56	F61074-V8070-Z000

Electrostactic **S**ensitive **D**evice (**ESD**)

Maximum ratings

Operable temperature range	T_A	–45/+90	˚C	
Storage temperature range	T_{stg}	–45/+90	˚C	
DC voltage	V_{DC}	0	V	
Source power	P_S	0	dBm	source impedance 50 Ω

Data Sheet

Characteristics

Reference temperature: T_A = 25 °C
Terminating source impedance: Z_S = 50 Ω and matching network
Terminating load impedance: Z_L = 50 Ω and matching network

		min.	typ.	max.	
Center frequency (center frequency between 3 dB points)	f_C	—	345,03	—	MHz
Minimum insertion attenuation	α_{min}				
344,90 ... 345,10 MHz		—	2,0	3,0	dB
Pass band (relative to α_{min})					
344,94 ... 345,13 MHz		—	0,8	2,0	dB
344,90 ... 345,17 MHz		—	1,0	3,0	dB
344,87 ... 345,20 MHz		—	1,5	6,0	dB
Relative attenuation (relative to α_{min})	α_{rel}				
10,00 ... 300,00 MHz		45	50	—	dB
300,00 ... 341,00 MHz		40	45	—	dB
341,00 ... 344,00 MHz		15	20	—	dB
346,10 ... 347,00 MHz		10	15	—	dB
347,00 ... 350,00 MHz		20	25	—	dB
350,00 ... 450,00 MHz		35	40	—	dB
450,00 ... 1000,00 MHz		45	50	—	dB
Impedance for pass band matching					
Input: $Z_{IN} = R_{IN} \parallel C_{IN}$		—	350 ‖ 2,80	—	Ω || pF
Output: $Z_{OUT} = R_{OUT} \parallel C_{OUT}$		—	350 ‖ 2,80	—	Ω || pF
Temperature coefficient of frequency [1]	TC_f	—	–0,03	—	ppm/K²
Frequency inversion point	T_0	10	—	30	°C

[1] Temperature dependence of f_C: $f_C(T_A) = f_C(T_0)\ (1 + TC_f(T_A - T_0)^2)$

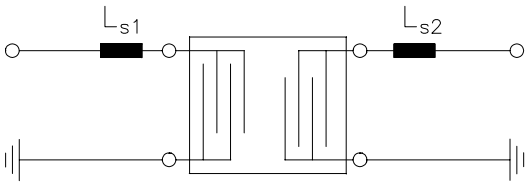
Data Sheet

Characteristics

Reference temperature: T_A = –45 ... 90 °C
Terminating source impedance: Z_S = 50 Ω and matching network
Terminating load impedance: Z_L = 50 Ω and matching network

		min.	typ.	max.	
Center frequency (center frequency between 3 dB points)	f_C	—	345,00	—	MHz
Minimum insertion attenuation	α_{min}				
344,90 ... 345,10 MHz		—	2,0	3,5	dB
Pass band (relative to α_{min})					
344,94 ... 345,06 MHz		—	0,8	2,0	dB
344,90 ... 345,10 MHz		—	1,0	3,0	dB
344,87 ... 345,13 MHz		—	1,5	6,0	dB
Relative attenuation (relative to α_{min})	α_{rel}				
10,00 ... 300,00 MHz		45	50	—	dB
300,00 ... 341,00 MHz		40	45	—	dB
341,00 ... 343,93 MHz		15	20	—	dB
346,10 ... 347,00 MHz		10	15	—	dB
347,00 ... 350,00 MHz		20	25	—	dB
350,00 ... 450,00 MHz		35	40	—	dB
450,00 ... 1000,00 MHz		45	50	—	dB
Impedance for pass band matching					
Input: $Z_{IN} = R_{IN} \parallel C_{IN}$		—	350 ‖ 2,80	—	Ω ‖ pF
Output: $Z_{OUT} = R_{OUT} \parallel C_{OUT}$		—	350 ‖ 2,80	—	Ω ‖ pF

Matching network to 50 Ω (element values depend on pcb layout and equivalent circuit**)**



L_{s1} = 47 nH

L_{s2} = 47 nH

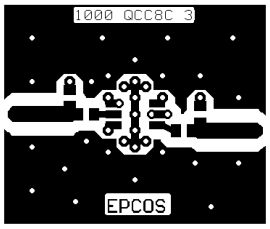
Minimising the crosstalk

For a good ultimate rejection a low crosstalk is necessary. Low crosstalk can be realised with a good RF layout. The major crosstalk mechanism is caused by the “ground-loop” problem.

Grounding loops are created if input-and output transducer GND are connected on the top-side of the PCB and fed to the system grounding plane by a common via hole. To avoid the common ground path, the ground pin of the input- and output transducer are fed to the system ground plane (bottom PCB plane) by their own via hole. The transducers’ grounding pins should be isolated from the upper grounding plane.

A common GND inductivity of 0.5nH degrades the ultimate rejection (crosstalk) by 20dB.

The optimised PCB layout, including matching network for transformation to 50 Ohm, is shown here. In this PCB layout the grounding loops are minimised to realise good ultimate rejection.

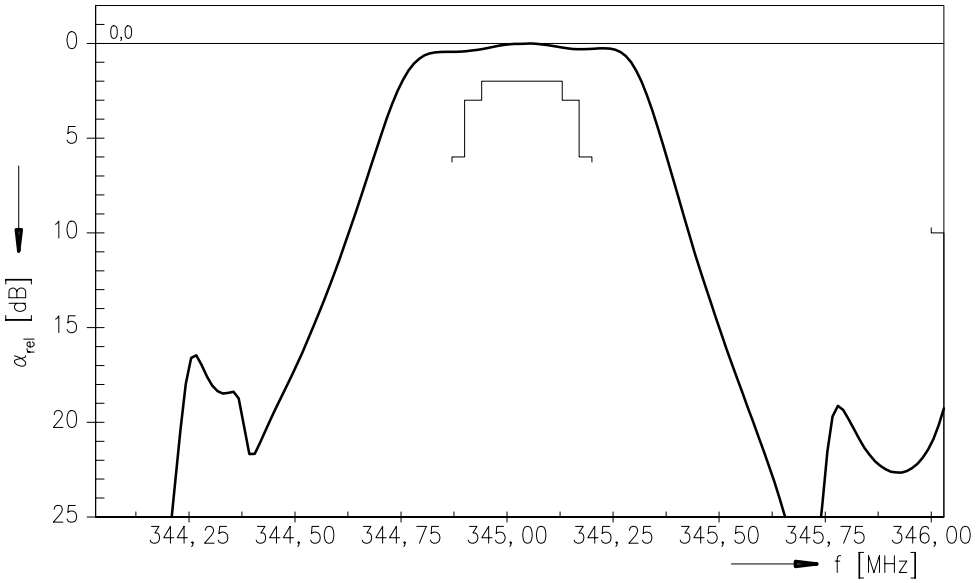


Optimised PCB layout for SAW filters in QCC8C package, pinning 2,5 (top side, scale 1:1)

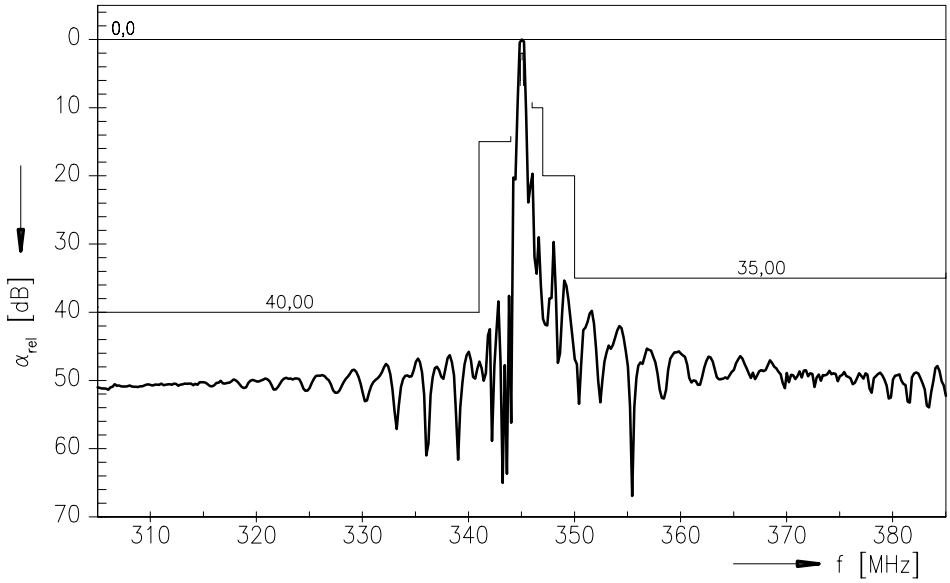
The bottom side is a copper plane (system ground area). The input and output grounding pins are isolated and connected to the common ground by separated via holes.

For good contact of the upper grounding area with the lower side it is necessary to place enough via holes.

Normalized frequency response



Normalized frequency response (wideband)



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